

Datasheet

FS8820S

Dual N-Channel Enhancement Mode Power MOSFET

FORTUNE,
Properties,
For Reference Only

Fortune Semiconductor Corporation

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1. Features

1.1 Low on-resistance

1.1.1 $R_{DS(ON)} = 24\text{ m}\Omega$ MAX. ($V_{GS} = 4.5\text{V}$, $I_D = 6\text{A}$)

1.1.2 $R_{DS(ON)} = 32\text{ m}\Omega$ MAX. ($V_{GS} = 2.5\text{V}$, $I_D = 5\text{A}$)

1.1.3 ESD Rating: $\geq 2000\text{V}$ HBM

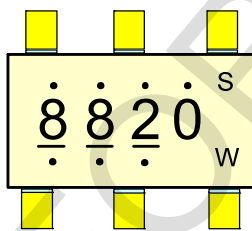
2. Applications

- Li-ion battery management applications

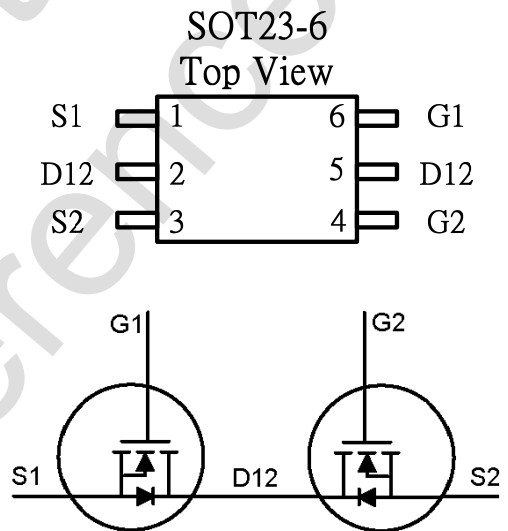
3. Ordering Information

Product Number	Description	Package Type	Quantity/Reel
FS8820S	SOT-23-6 version	SOT-23-6	3,000

4. Pin Assignment



For FS8820S
 w : A~Z or A ~ Z
 Top points, bottom points & w: Lot No Information



5. Limiting Values

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	20	V
VGS	Gate-Source Voltage	± 12	V
ID @TA = 25°C	Continuous Drain Current ³	6.5	A
ID @TA = 100°C	Continuous Drain Current ³	4	A
IDM	Pulsed Drain Current ¹	20	A
PD @TA = 25°C	Total Power Dissipation	1.25	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Is	Diode Forward Current	1.7	A

6. Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Thermal Resistance Junction-ambient3	Max. 125	°C/W

7. Electrical Characteristics

Electrical Characteristics @TA = 25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250uA	20	-	-	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.1	-	V/°C
R _{DS(ON)} ¹	Static Drain-Source On-Resistance ²	V _{GS} = 4.5V, I _D = 6A	-	19	24	mΩ
		V _{GS} = 2.5V, I _D = 5A	-	25	32	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250uA	0.5	0.7	1.0	V
I _{DSS}	Drain-Source Leakage Current (T _J = 25°C)	V _{DS} = 16 V _{GS} = 0V	-	-	1	uA
	Drain-Source Leakage Current (T _J = 85°C)	V _{DS} = 16 V _{GS} = 0V	-	-	30	uA
I _{GSS}	Gate-Source Leakage	V _{GS} = ±10V	-	-	±10	uA
Diode Characteristics						
V _{SD} ¹	Diode Forward Voltage	I _{SD} =1.7A, V _{GS} =0V		0.7	1.0	V
t _{rr}	Reverse Recovery Time	I _{SD} =6A, dI _{SD} /dt=100A/μs		27		Ns
Q _{rr}	Reverse Recovery Charge			15		nC
Dynamic Characteristics²						
R _G	Gate Resistance	V _{GS} =V _{DS} =0V, F=1MHz		4		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V Frequency=1MHz		1110		pF
C _{oss}	Output Capacitance			240		
C _{rss}	Reverse Transfer Capacitance			200		
t _{d(on)}	Turn-on Delay Time	V _{DS} =10V, V _{GEN} =4.5V, R _G =6Ω, R _L =10Ω, I _{DS} =1A		6	12	ns
t _r	Turn-on Rise Time			13	24	
t _{d(off)}	Turn-off Delay Time			67	122	
t _f	Turn-off Rise Time			37	68	
Gate Charge Characteristics²						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _{DS} =6A		15	21	nC
Q _{gs}	Gate-Source Charge			1.5		
Q _{gd}	Gate-Drain Charge			4.7		

Notes :

1. Pulse width ≤ 300us, duty cycle ≤ 2%.
2. Guaranteed by design, not subject to production testing

8. Typical Characteristics

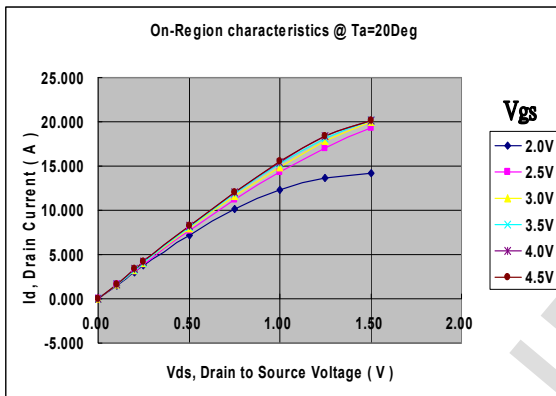


Fig 1. Typical Output Characteristics

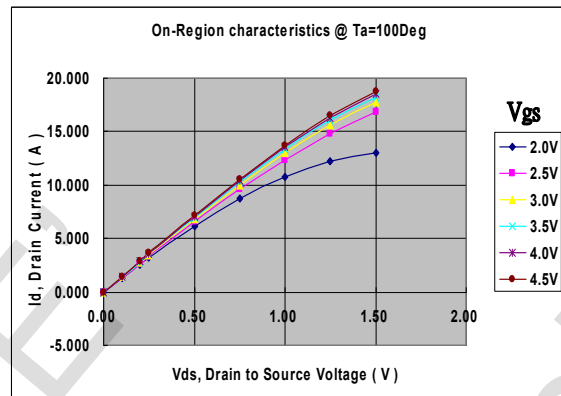


Fig 2. Typical Output Characteristics

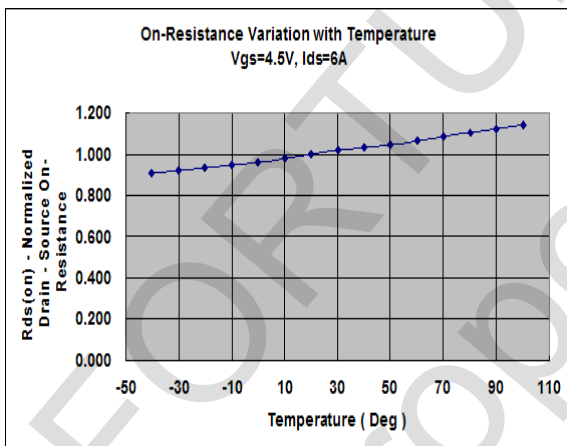


Fig 3. Normalized On-Resistance

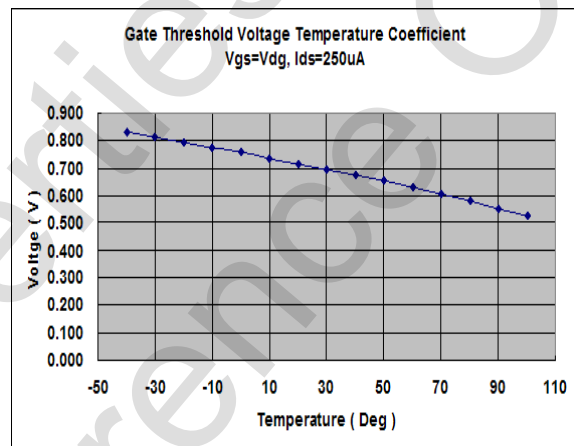


Fig 4. Gate Threshold Variation with Temperature

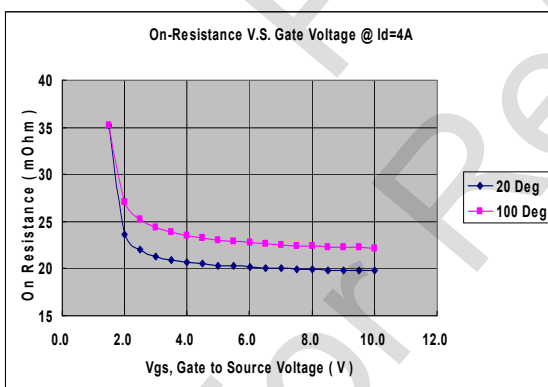
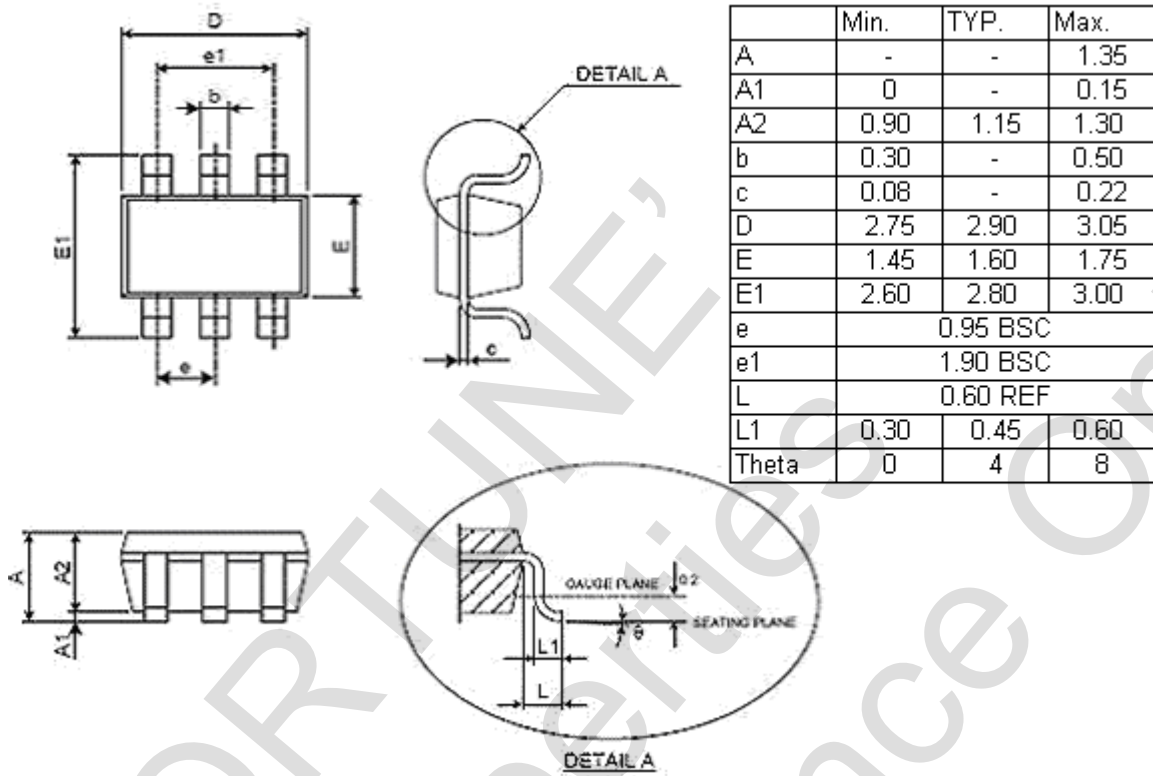


Fig 5. Forward Characteristic of Reverse Diode

9. Package Information



10. Revision History

Version	Date	Page	Description
1.0	2011/12/26	ALL	New release
1.1	2012/12/10	6	Revise Package Information A
1.2	2014/05/22	2	Revised company address
1.3	2016/08/29	3	Revise Package Marking Information